IN THE SPECIFICATION:

The specification as amended below with replacement paragraphs shows added text with <u>underlining</u> and deleted text with <u>strikethrough</u>.

Please DELETE the entire contents of the paragraph beginning at page 7, line 15.

As another preferred feature, the elastic member, while being in contact with the printed wiring board, is attached around the component package by pressure due to the elastic deformation of the elastic member.

Please DELETE the entire contents of the paragraph beginning at page 8, line 22.

As another preferred feature, the elastic member, while being in contact with the printed wiring board, is attached around the component package by pressure due to the elastic deformation of the elastic member.

Please REPLACE the paragraph beginning at page 11, line 21, with the following paragraph:

FIG. 2(a) and FIG. 2(b) are views for describing illustrates the size of the spacer of the first embodiment of the present invention;

FIG. 2(b) illustrates the undersurface of the body of an IC package to which the spacer of FIG. 2(a) is attached.

Please REPLACE the paragraph beginning at page 13, line 16, with the following paragraph:

FIG. 1 depicts a spacer according to a first preferred embodiment of the present invention. FIG. 2(a) and FIG. 2(b) are is a view illustrating the size of the spacer of the first embodiment; the former is for describing the size of the spacer, and the latter and FIG. 2(b) illustrates depicts the undersurface of the body of an IC package which the spacer of the first embodiment is attached to. Further, FIG. 3(a) and FIG. 3(b) are views for describing such a spacer of the first embodiment mounted on a printed wiring board; the former is a plan view, and the latter is the cross section Z-Z of the former.